

MIL-HDBK-217可靠性预计方法存在的问题及其替代方法浅析

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摘要: 简要分析了基于MIL-HDBK-217传统可靠性预计方法中存在的问题,对目前在工业界颇受重视的基于失效物理的可靠性评估方法进行了研究.

关键词: 可靠性预计;失效物理;方法

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A Simple Analysis on the Problems Existing in the Methods for Estimating Reliability in MIL-HDBK-217 and the Alternative Methods

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